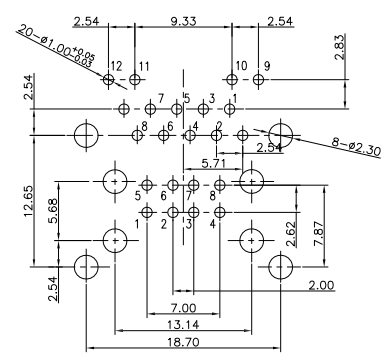
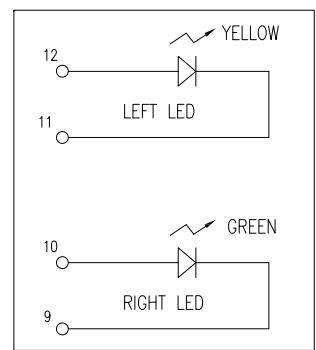
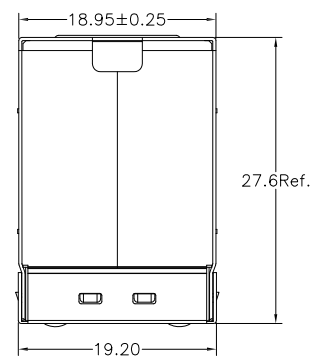


A



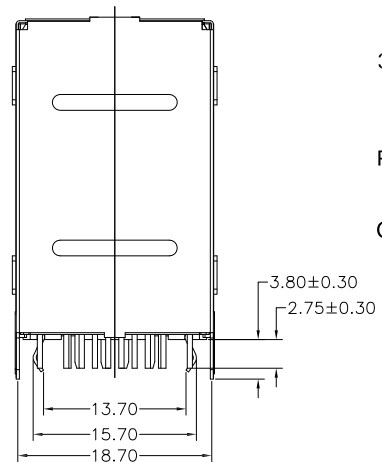
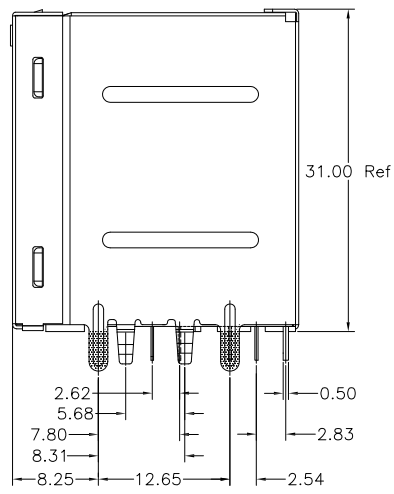
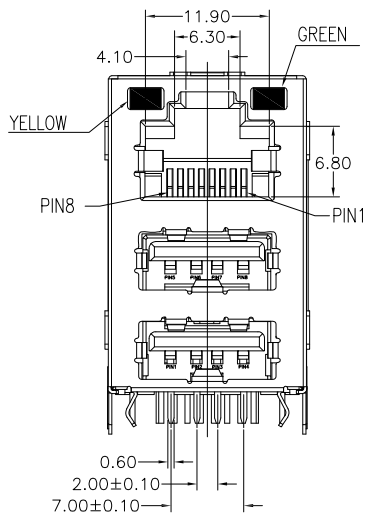
RECOMMENDED P.C.B. PATTERN LAYOUT
COMPONENT SIDE SHOWN

NOTES:

1. MATERIAL
 - 1.1 Housing: PBT, Black, UL94V-0
 - ① 1.2 Contact: Copper alloy, Tin plating 100u" on solder tail area, RJ45/USB Gold plating (see order code) on contact area, 30u" min Ni underplating over all
 - 1.3 Shell: SPCC
2. ELECTRICAL
 - 2.1 Rating Current: 1.5Amp
 - 2.2 Rating Voltage: 30VAC
 - 2.3 Contact Resistance: ≤30mΩ
 - 2.4 Insulator Resistance: ≥1000MΩ
 - 2.5 Dielectric withstanding voltage: 500V AC
3. Environment:
 - 3.1 Temperature Range: -55°C~ +85°C
 - 3.2 Soldering Temperature: +220°C max.

B

C



Package: Tray

Order Code:

- ① A-MJU-8-RA-xTP-SGY1
 - K = Gold flash selective tin
 - P = 15u" Au/Sn
 - H = 30u" Au/Sn

D

E

F

G

H

RoHS compliant
Unit: mm

Scale	Free					Date	Name	
TOLERANCE						Drawn	01.04.2019	Amy
X.X	±0.30					Approved	02.06.2021	Luca
X.XX	±0.20							
X.XXX	±0.10							
DIM	TOL	①	Add new PNs for new plating	02.06.2021	Luca			
X.XX	±2°	②	Drawn	01.04.2019	Amy			
X.X	±3°							
Angle	TOL	Id.	Modification	Date	Name			

Description: RJ45 Modular + USB 2.0 Type A Female / THT / R/A

ASSMANN WSW-No.
① A-MJU-8-RA-xTP-SGY1

Drawing-No.	ASS 8368 CO	rev01
Customer-No.		Sheet